



## CMS SLHC Tracker Thin Sensor R&D with HPK



November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

CERN



## Outline plan of work for Sensors



- **Phase I: Targeted R&D** ~ 2008 - 2012
  - Establish required sensors characteristics & basic specifications
  
- **Phase II: Preproduction and Qualification** ~ 2012 - 2014
  - Finalize detailed specifications and QA protocols
  - Qualify for large scale production
  
- **Phase III: Large Scale Production** ~ 2014 - 2016
  
- **Market Survey to identify Additional Industrial Partners for Phases II and III**
  - Producers qualified according to this MS may take part in Phase II
  - Production contingent on Phase II success



## Outline plan of work for Sensors



- **Phase I: Targeted R&D** ~ 2008 - 2012
  - Establish required sensors characteristics & basic specifications
  - Funds available and Cost for HPK order now match
  - Negotiating Single Source HPK order with CERN
  - Layout still being finalized...
- **Phase II: Preproduction and Qualification** ~ 2012 - 2014
  - Finalize detailed specifications and QA protocols
  - Qualify for large scale production
- **Phase III: Large Scale Production** ~ 2014 - 2016
- **Market Survey to identify Additional Industrial Partners for Phases II and III**
  - Producers qualified according to this MS may take part in Phase II
  - Production contingent on Phase II success



## CMS SLHC Tracker Thin Sensor R&D with HPK



- **Aim for:**
  - **Single Technology for Outer Tracking Layers**
  - **Single Technology for Inner Pixel Layers**
    - This will be an important consideration in defining Radial Boundary between these two Regions
- **For the region above ~ 22cm, currently occupied by the Strip Tracker, a program of measurements is proposed, addressing**
  - **Thin Single-Sided p-on-n vs n-on-p sensors on FZ vs MCZ**
- **Based on results obtained, aim to identify Radial Regions where these technologies can be deployed**



# CMS SLHC Tracker Thin Sensor R&D with HPK



nb active thickness ~ physical thickness - 20um

substrate type & physical thickness	FZ 200um carrier	MCZ 200um thinning	FZ 120um carrier	epi 100um	epi 60um	FZ 320um	Total
P-on-N Production	6	6	6	6	6	14	44
N-on-P Production p-spray	6	6	6	6	6	14	44
N-on-P Production p-stop	6	6	6	6	6	14	44
2'nd metal production P-on-N	6						6
2'nd metal production N-on-P p-stop	6						6
<b>Total</b>	<b>30</b>	<b>18</b>	<b>18</b>	<b>18</b>	<b>18</b>	<b>43</b>	<b>145</b>



## Backup Slides



November 2008




Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

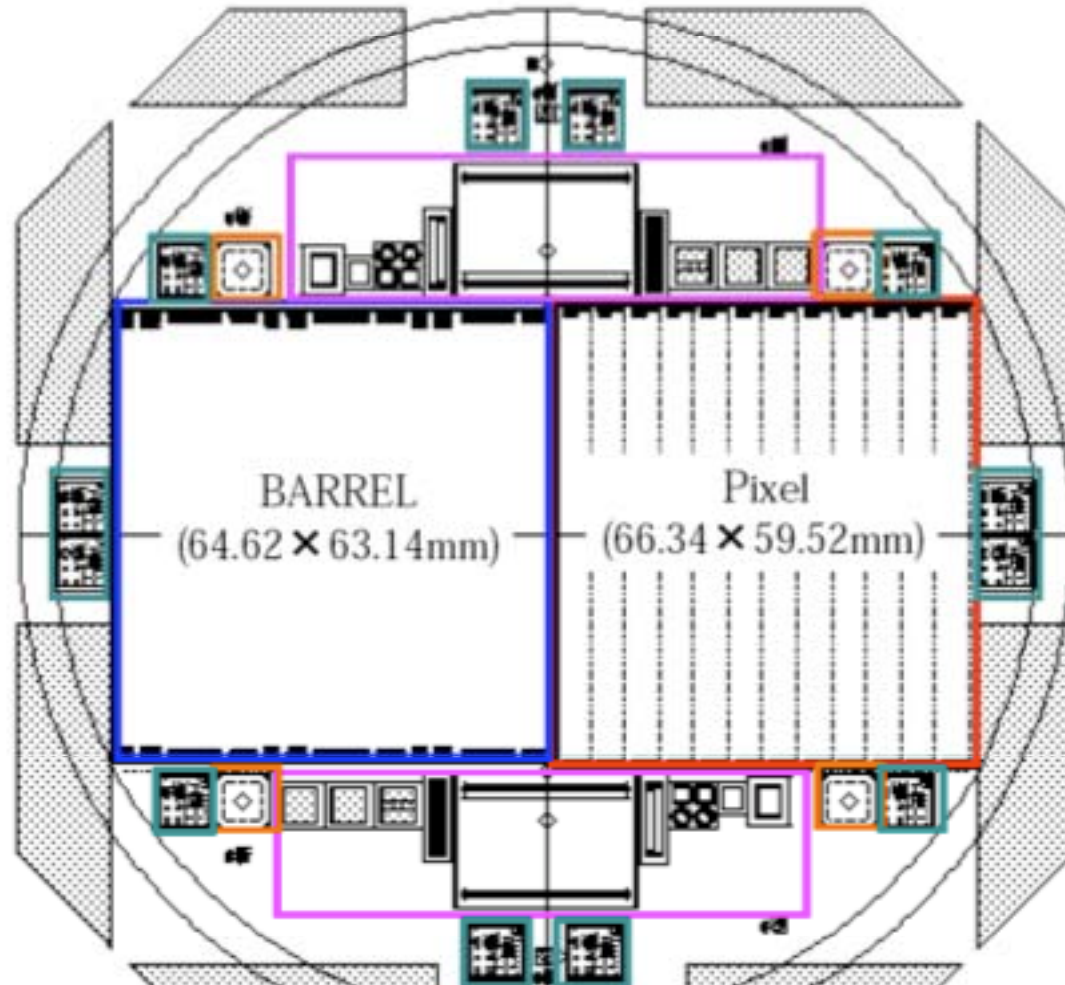
CERN



## CMS SLHC Tracker Thin Sensor R&D with HPK



-  Previous Test Structure
-  Monitor Diode
-  HPK Test structure



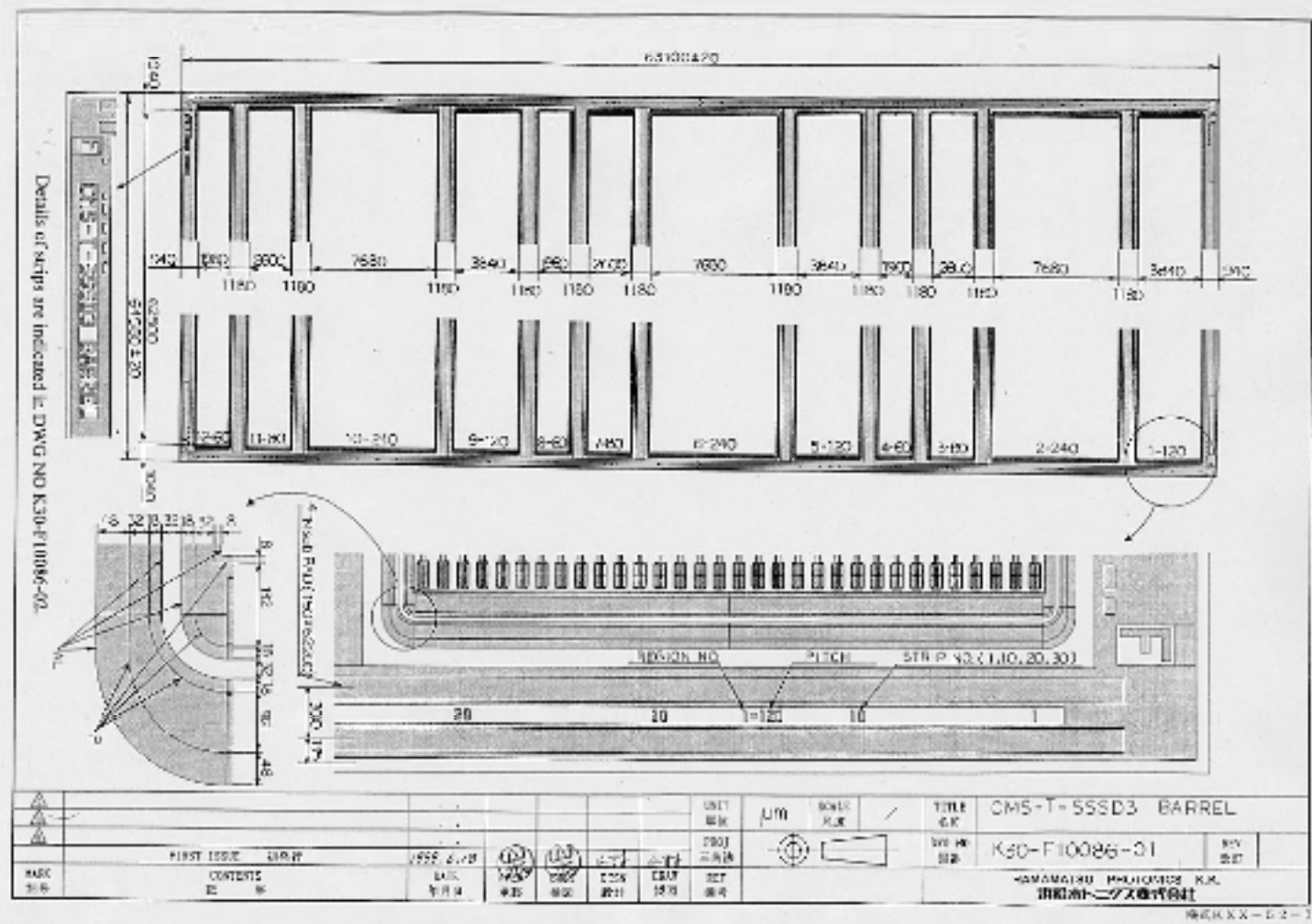
November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

CERN



# Multi-Geometry Strip Sensors



November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor R&D with HPK

CERN





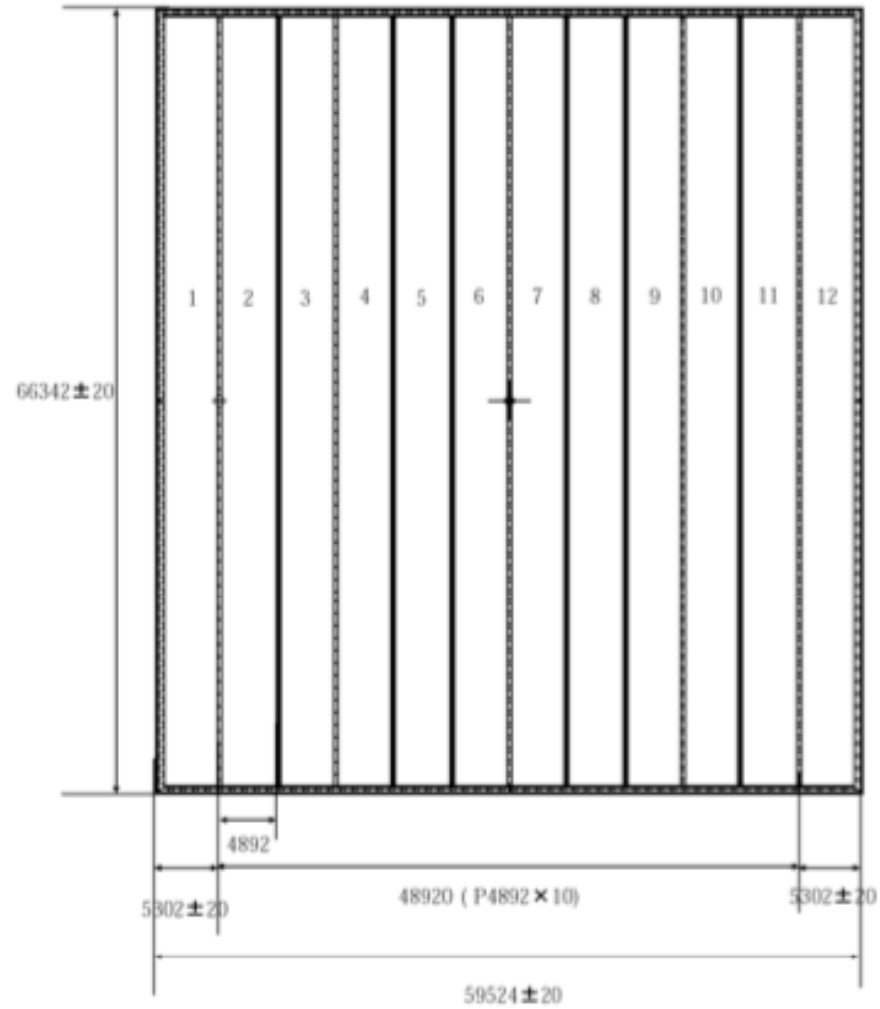
## Multi-Geometry Long Pixel Sensors



- **Pixel pitch:** **120um**
- **Pixel implant width / pixel pitch:** **0.25**
- **Metal overhang:** **8 um**
- **Pixel separation, along pixel length:** **60um; 90um; 120 um**
- **Pixel length:** **1mm; 2mm; 3mm; 4mm**



## Multi-Geometry Long Pixel Sensors



November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

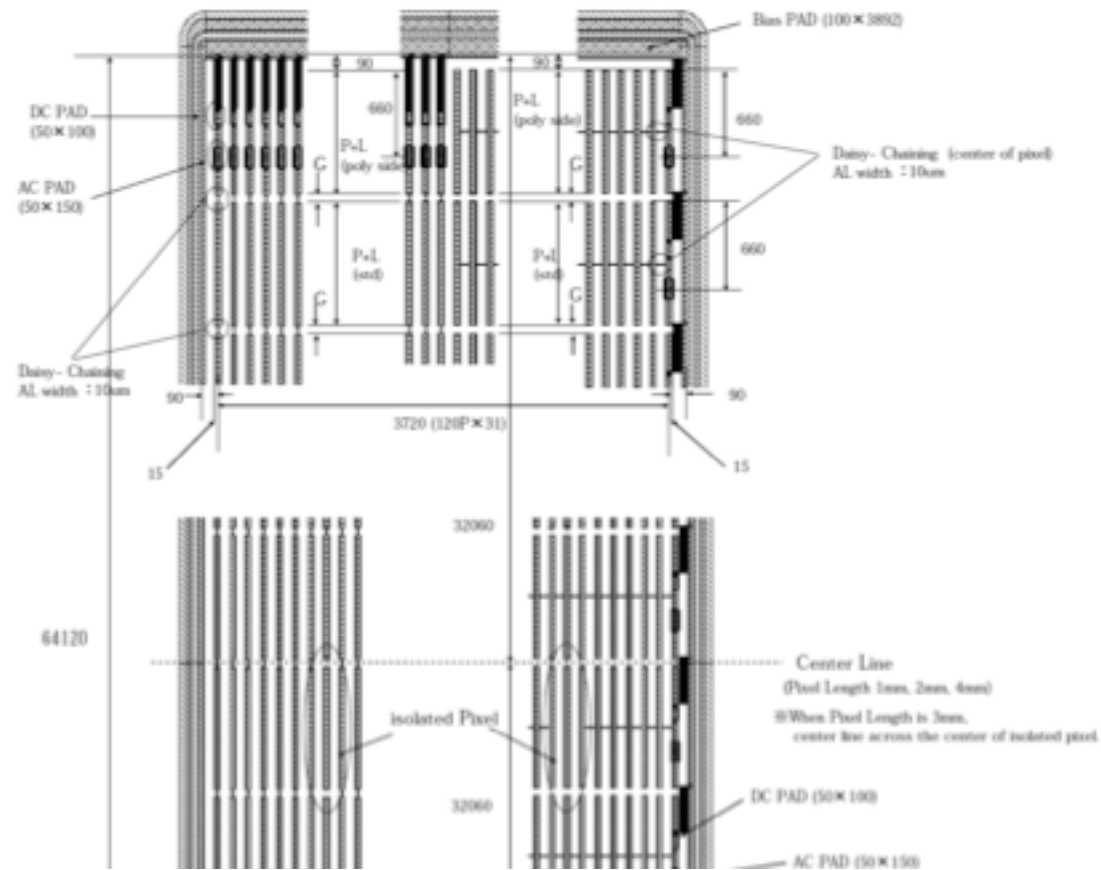
CERN



# Multi-Geometry Long Pixel Sensors



Pixel Length = (P+ Length) + (Gap)	1000			2000			3000			4000		
Number of wires/row	64			32			21			16		
G	Gap			Gap			Gap			Gap		
P+ Length (std)	940	910	880	1940	1910	1880	2940	2920	2900	3940	3910	3880
P+ Length (poly side)	980			1940			2980			3940		



November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

CERN



## Long Pixels Biasing Scheme i



Pixel Implants:

Length 1 ~ 4mm

Pitch ~ 120um

Width ~ 30um

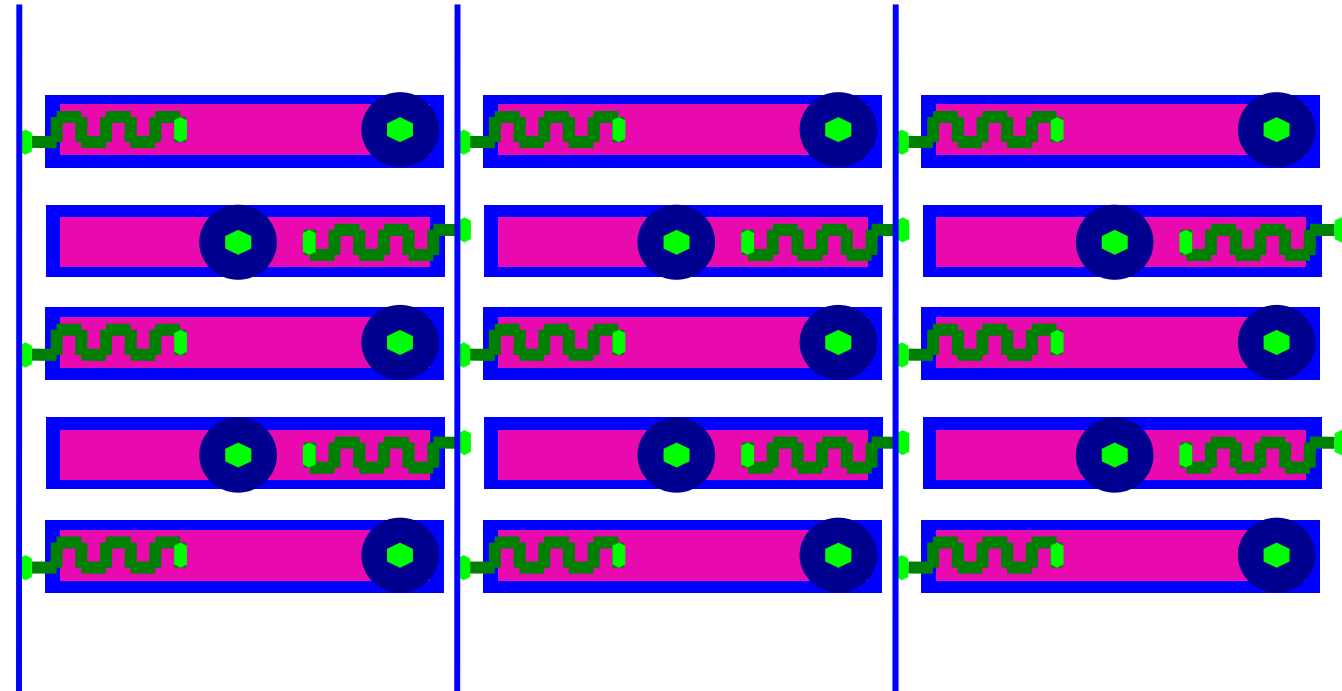
Gaps ~ 90um

Vias:

Metal – Poly

Poly – Implant

Metal - Implant



Poly Bias Resistors:

~ 1M $\Omega$ m

Metal Layer:

Bump min. pitch ~ 240um

Bump Diameter ~ 50um

Bias Line Width < 10um



## Long Pixels Biasing Scheme ii



Pixel Implants:

Length 1 ~ 4mm

Pitch ~ 120um

Width ~ 30um

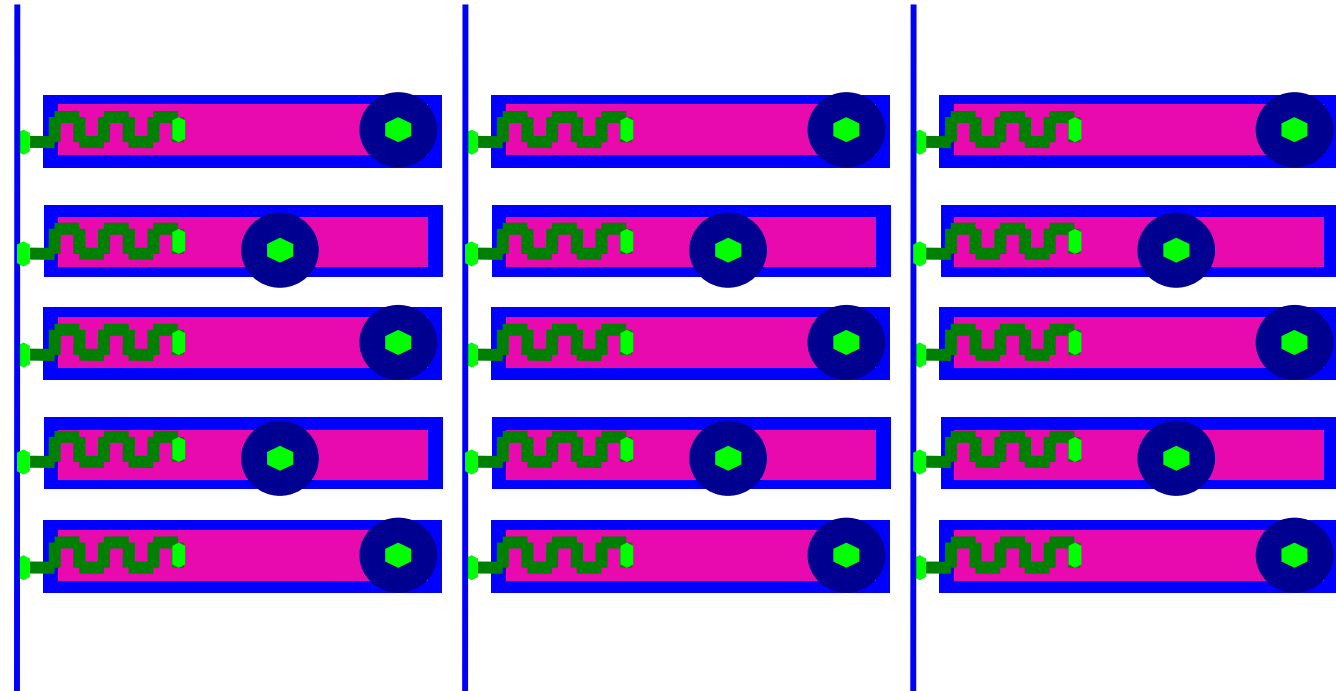
Gaps ~ 90um

Vias:

Metal – Poly

Poly – Implant

Metal - Implant



Poly Bias Resistors:

~ 1M $\Omega$ m

Metal Layer:

Bump min. pitch ~ 240um

Bump Diameter ~ 50um

Bias Line Width < 10um



**More Backup slides**



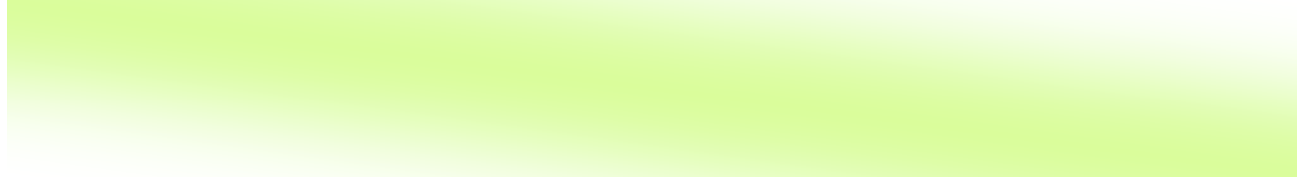
November 2008

Marcello Mannelli CMS SLHC Tracker Thin Sensor  
R&D with HPK

CERN



- **The charged hadron fluence has a strong radial dependence; the neutral hadron fluence, in particular above about 60cm has little radial dependence**
- **For radii below 60cm, the fluence is dominated by charged pions; at about 70cm, the fluence of charged pions and neutral hadrons are approximately equal**
  - **This motivated the TIB/TOB thin/thick sensor transition**
- **There is factor of almost 6 reduction in total fluence going from 22cm to 58cm radius**
- **There is a further factor of about 2 in going from 58cm to 115cm radius**
- **The fluence at 4cm radius is almost 20 times higher than at 22cm radius**

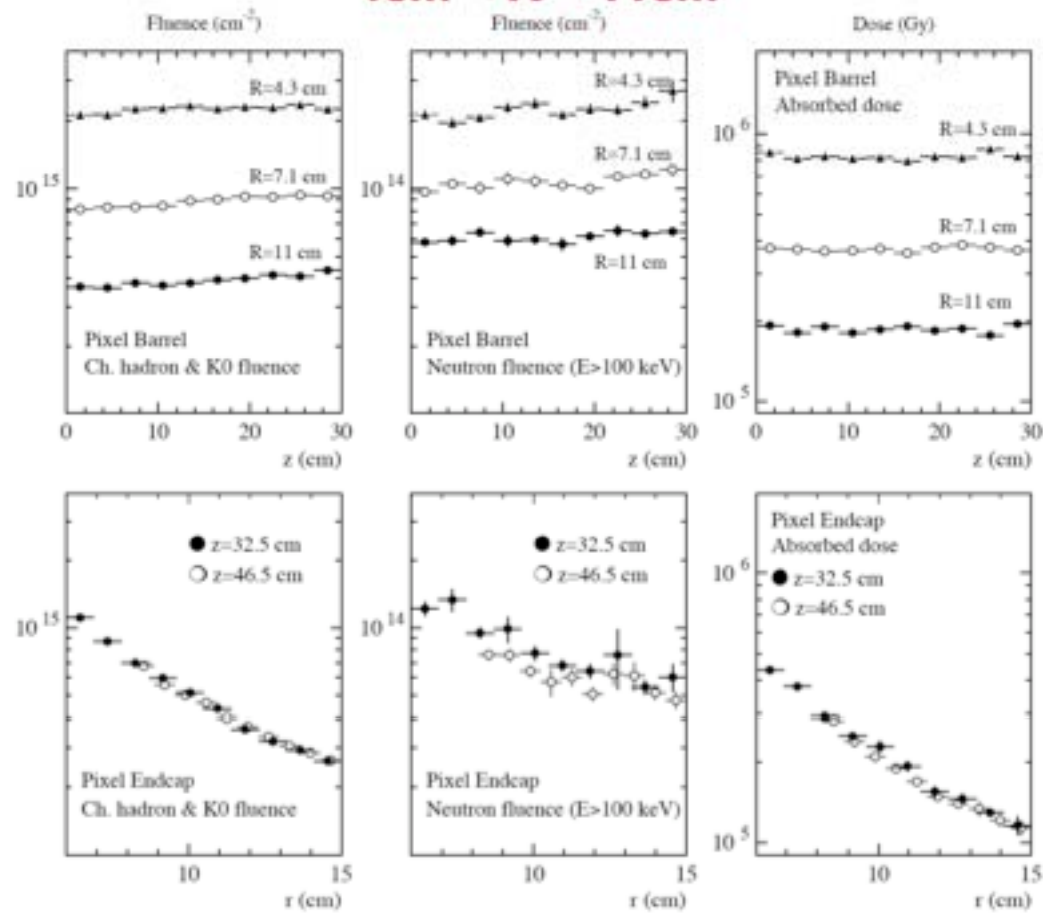


- **At the SLHC, the fluence at the innermost radius of TIB (22cm) will be about half as much as at the innermost Pixel layer at full LHC luminosity**
- **At the SLHC, the fluence at the innermost (outermost) radius of the TOB will be about 2.5 (1.1) times higher than at innermost radius of TIB at full LHC luminosity**



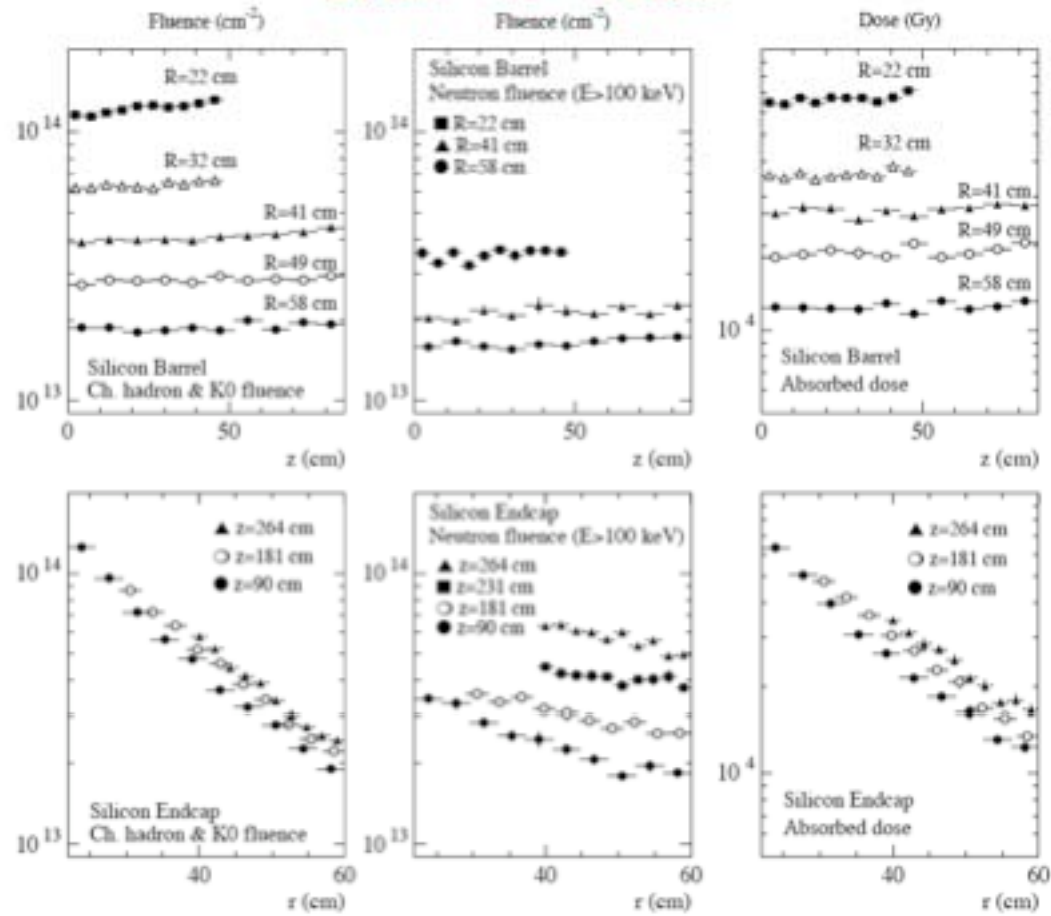


## 4cm < R < 11cm



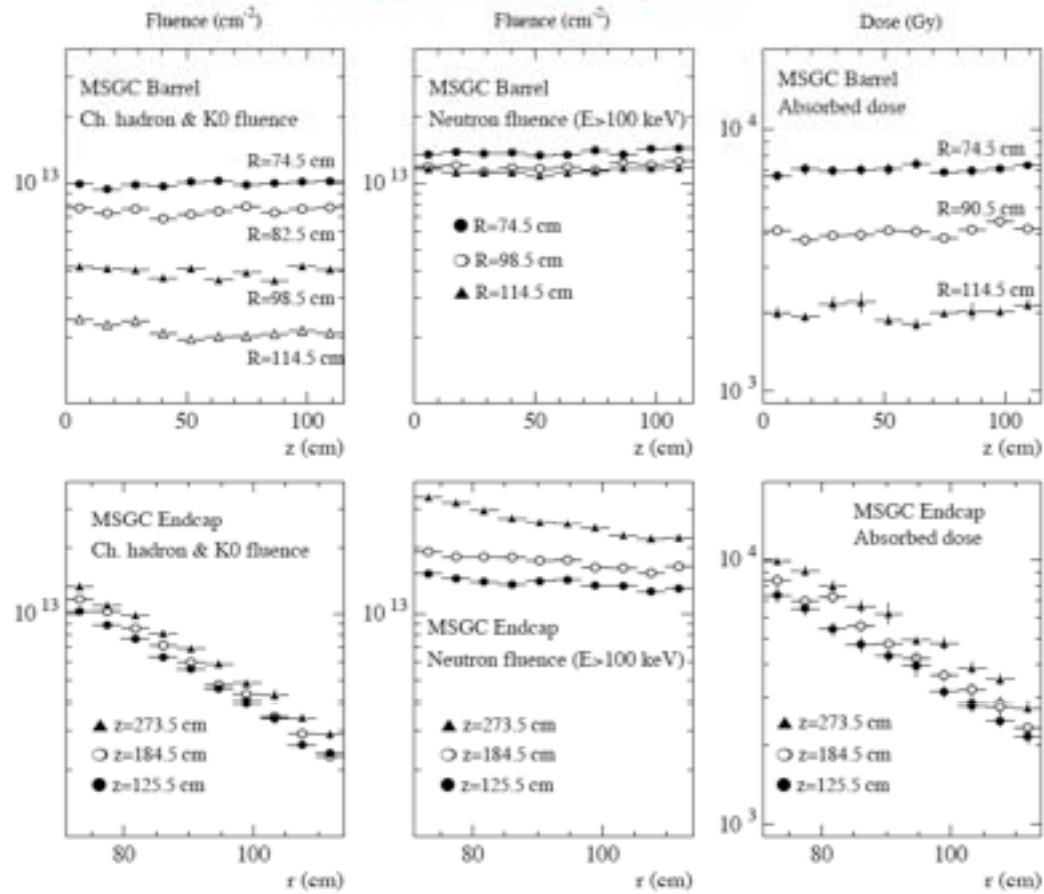


## 20cm < R < 60cm





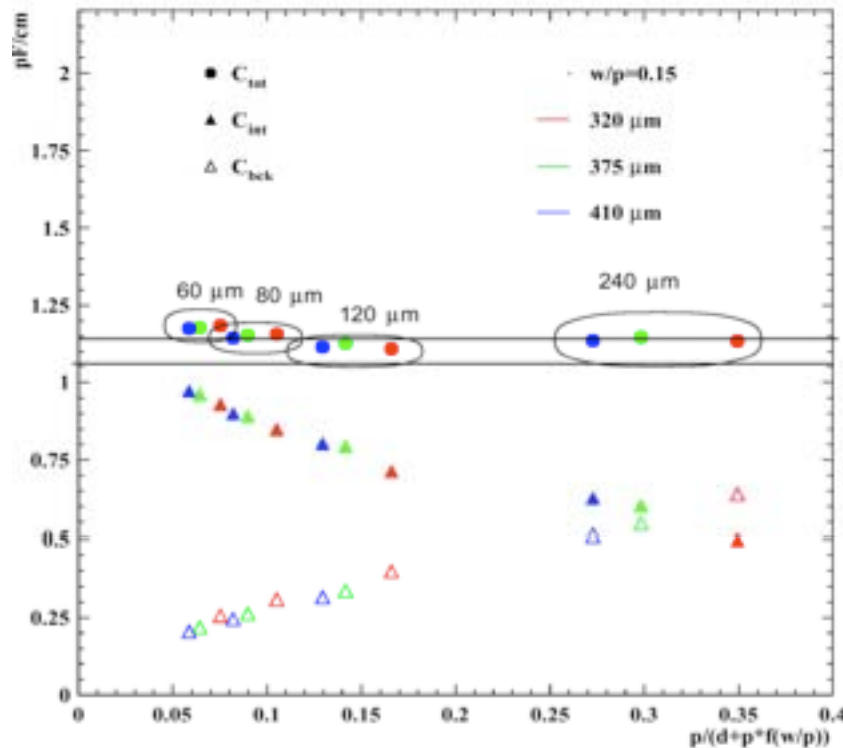
## 75cm < R < 115cm





**Total Strip capacitance is the main contribution to electronic noise**  
**It is a function of w/p only, Independent of pitch and thickness**

**$C_{tot} \sim 1.2 \text{ pF/cm}$  for  $w/p = 0.25$**



**Noise  $\sim 430e^- + 75e^- * \text{strip length cm}$**

